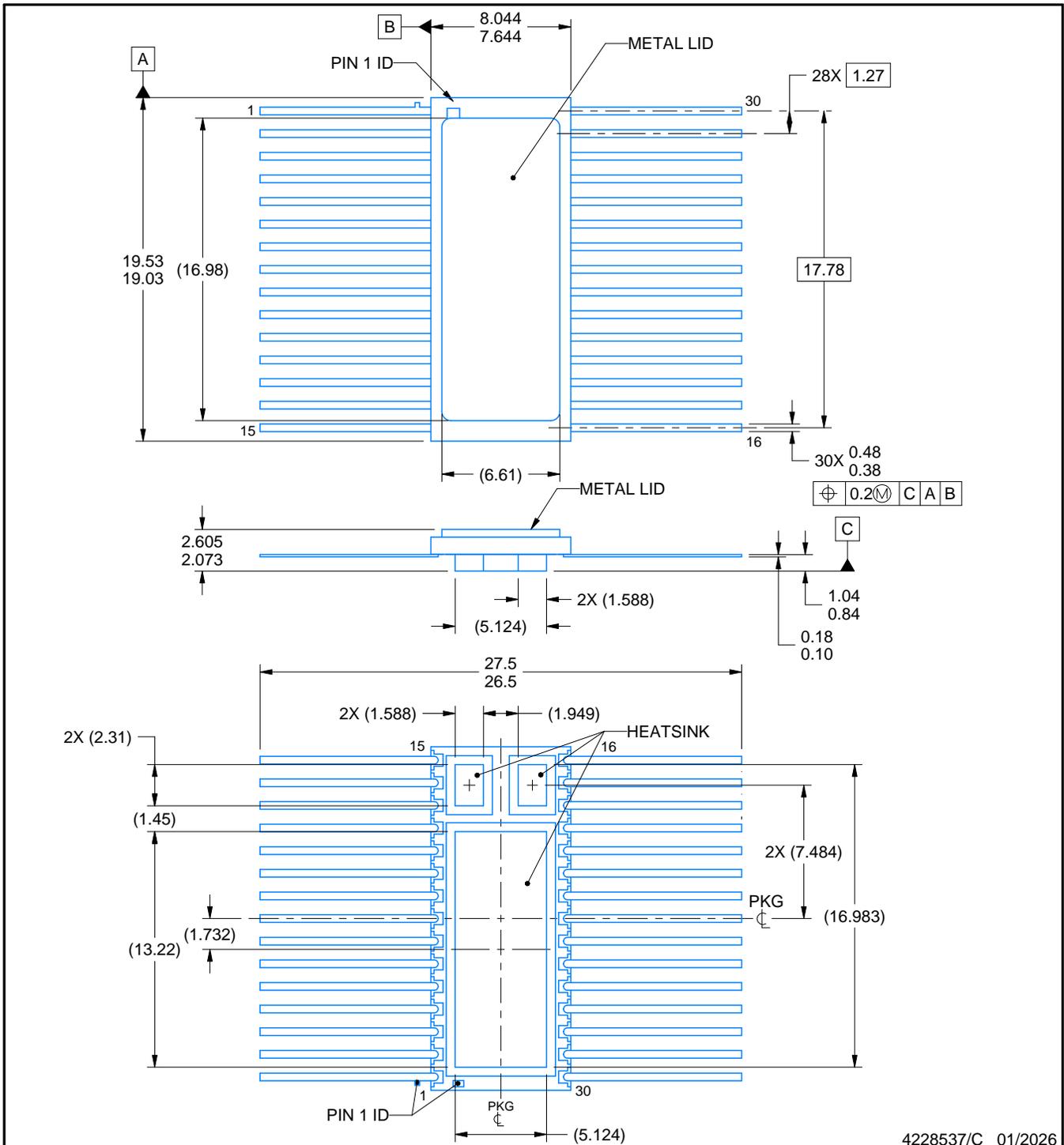


PACKAGE OUTLINE

HLB0030A

CFP - 2.605 mm max height

CERAMIC DUAL FLATPACK



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NOTES:

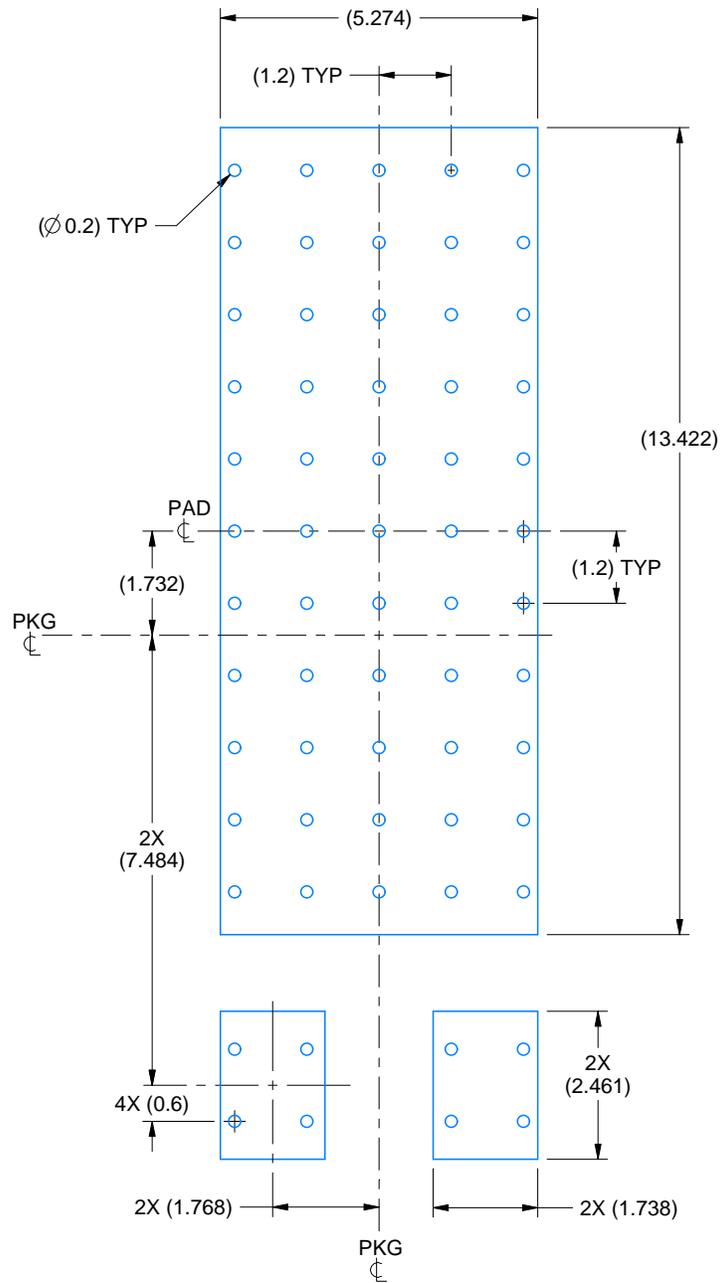
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The terminals are gold plated.
5. Falls within MIL-STD-1835 CDFP-F11A.

EXAMPLE BOARD LAYOUT

HLB0030A

CFP - 2.605 mm max height

CERAMIC DUAL FLATPACK



HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X

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REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2198923	03/16/2022	R. RAZAK / ANIS FAUZI
B	CORRECT PIN COUNT ON COVER PAGE TITLE	2199987	05/18/2022	R. RAZAK / K. SINCERBOX
C	ADD EXTRA REFERENCE DIMENSIONS TO LOCATE BOTTOM HEATSINKS; REMOVE UNNECESSARY REFERENCE DIMENSIONS;	2215799	01/22/2026	R. RAZAK / K. SINCERBOX

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Last updated 10/2025